Product Change Notification

112129 - 00

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The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: **112129 - 00**

Change Title: **Intel® BlueMoon Universal ™ - PCN112129-00 - PMB8763 -V1.1 Change of Assembly Site**

Date of Publication: **March 15, 2013**

Key Characteristics of the Change:

Assembly Site Transfer from ATP to ASEK with a change in BOM

Forecasted Key Milestones:

Date of Samples Availability:	May 01, 2013
Date of Qualification Data Availability:	August 18, 2013
Date Customer Must be Ready to Receive Post-Conversion Material:	October 1, 2013

The date of " Date Customer Must be Ready to Receive Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

In order to secure capacity and flexibility regarding long term customer demand, Intel wants to change production assembly supplier from Amkor to ASE with change in BOM as listed below:

	Before PCN	With PCN
▪ **Assembly Site**	**Amkor Philipphine**	**ASE Taiwan**
▪ **Bonding Wire**	**Au Wire (25um)**	**Cu Wire (25um)**
▪ **Mold Compound**	**Sumitomo EMEG770**	**Kyocera G1250LKDS**
▪ **Die Attached Epoxy**	**Ablebond 2300**	**Ablebond 2100**
▪ **Solder Ball**	**96.5Sn3.5Ag**	**SAC1205**

Customer Impact of Change and Recommended Action:

Intel does not anticipate any change on the package size, function, manufacturability or reliability. The new package will be qualified at Intel. The qualification results will be provided in the given schedule.
All materials are qualified and in volume production at several products what results in a mature product for customer.
The bond wire material changes from Au to Cu with same bond diameter. Intel does not see a risk on electrical performance variation due to this change.
Recommended action to customer is to verify and qualify the change in customer’s product.

Please contact your local Intel Mobile Communications representative for further technical questions.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	S-Spec	MM#
Intel® BlueMoon™	PMB8763AV1.00	SLJSJ	922050
Intel® BueMoon™	PMB8763AXV1.00	SLJSK	922051

BlueMoon™

PCN Owner

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PCN Revision History:

Date of Revision:	Revision Number:	Reason:
March 15, 2013	00	Originally Published PCN